molex

Part Number : 2091411110

Product Description : Mirror Mezz Hermaphroditic Connector, 2.50mm Connector Height, 10 Pair, 11 Row, 468 Circuits, 0.76µm Gold (Au) Plating

Series Number : 209141

Status : Active

Product Category : Board-to-Board Connectors

Documents & Resources

Drawings

Drawing 2091411110_sd.pdf

3D Models and Design Files

3D Model 2091411110_stp.zip
Electrical Model Document 2028281506EE-000.pdf
S-Parameter Model 2028281506SP-000.zip

Specifications

Application Specification 2028280001-AS-000.pdf
Application Specification 2028289005PS-001.pdf
Product Specification 2091410001-PS-000.pdf

Product Environment Compliance

Compliance

GADSL/IMDS	Not Relevant
China RoHS	e
EU ELV	Not Relevant
Low-Halogen Status	Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2023)8585-DC (23 Jan 2024)
EU RoHS	Compliant per EU 2015/863

Multiple Part Product Compliance Statements

- Eu RoHS
- REACH SVHC
- Low-Halogen

Multiple Part Industry Compliance Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

EU RoHS Certificate of Compliance

Part Details

General

Status	Active
Category	Board-to-Board Connectors
Series	209141
Description	Mirror Mezz Hermaphroditic Connector, 2.50mm Connector Height, 10 Pair, 11 Row, 468 Circuits, 0.76µm Gold (Au) Plating
Application	Board-to-Board
Component Type	PCB Header
Product Family	Mirror Mezz Connectors
Product Name	Mirror Mezz
UPC	193264207398

Agency

CSA	LR19980
UL	E29179

Electrical

Current - Maximum per Contact	0.75A (1 Oz Cu Trace), 1.2A (2 Oz Cu Trace)
Voltage - Maximum	30V AC (RMS)/DC

Physical

Breakaway	No
Circuits (Loaded)	468
Circuits (maximum)	468
Color - Resin	Black
Durability (mating cycles max)	100

First Mate / Last Break	No
Glow-Wire Capable	No
Guide to Mating Part	Yes
Keying to Mating Part	None
Lock to Mating Part	No
Mated Height	4.65mm
Material - Metal	High Performance Alloy (HPA)
Material - Plating Mating	Gold
Material - Plating Termination	BGA Solder
Material - Resin	High Temperature Thermoplastic
Net Weight	3.877/g
Number of Rows	11
Orientation	Vertical
Packaging Type	Embossed Tape on Reel
PCB Locator	Yes
PCB Retention	Yes
Pitch - Mating Interface	1.50mm, 4.00mm
Plating min - Mating	0.762µm
Polarized to Mating Part	Yes
Polarized to PCB	Yes
Temperature Range - Operating	-55° to +105°C
Termination Interface Style	Surface Mount

Solder Process Data

Max-Duration	10
Lead-Free Process Capability	REFLOW
Max-Cycle	1
Max-Temp	260